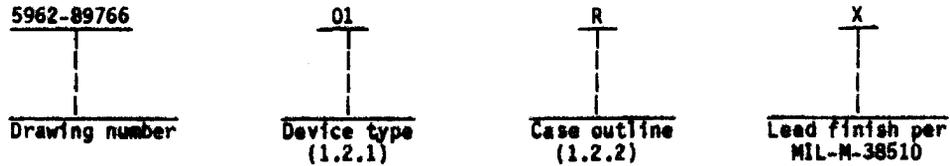




**SCOPE**

1.1 Scope. This drawing describes device requirements for class B microcircuits in accordance with 1.2.1 of MIL-STD-883, "Provisions for the use of MIL-STD-883 in conjunction with compliant non-JAM devices".

1.2 Part number. The complete part number shall be as shown in the following example:



1.2.1 Device types. The device types shall identify the circuit function as follows:

<u>Device type</u>	<u>Generic number</u>	<u>Circuit function</u>
01	54FCT541	Noninverting octal buffer/line driver with three-state output, TTL compatible
02	54FCT541A	Noninverting octal buffer/line driver with three-state output, TTL compatible

1.2.2 Case outlines. The case outlines shall be as designated in appendix C of MIL-M-38510, and as follows:

<u>Outline letter</u>	<u>Case outline</u>
R	D-8 (20-lead, 1.060" x .310" x .200"), dual-in-line package
S	F-9 (20-lead, .540" x .300" x .100"), flat package
Z	C-2 (20-terminal, .358" x .358" x .100"), square chip carrier package

1.3 Absolute maximum ratings. 1/

Supply voltage range - - - - -	-0.5 V dc to +7.0 V dc
Input voltage range - - - - -	-0.5 V dc to $V_{CC} + 0.5$ V dc
Output voltage range - - - - -	-0.5 V dc to $V_{CC} + 0.5$ V dc
DC input diode current ( $I_{IK}$ ) - - - - -	-20 mA
DC output diode current ( $I_{OK}$ ) - - - - -	-50 mA
DC output current - - - - -	+100 mA
Maximum power dissipation ( $P_D$ ) 2/ - - - - -	500 mW
Thermal resistance, junction-to-case ( $\theta_{JC}$ ) - - - - -	See MIL-M-38510, appendix C
Storage temperature range - - - - -	-65°C to +150°C
Junction temperature ( $T_J$ ) - - - - -	+175°C
Lead temperature (soldering, 10 seconds) - - - - -	+300°C

1.4 Recommended operating conditions.

Supply voltage range ( $V_{CC}$ ) - - - - -	+4.5 V dc to +5.5 V dc
Maximum low level input voltage ( $V_{IL}$ ) - - - - -	0.8 V dc
Minimum high level input voltage ( $V_{IH}$ ) - - - - -	2.0 V dc
Case operating temperature range ( $T_C$ ) - - - - -	-55°C to +125°C

1/ All voltages referenced to GND.

2/ Must withstand the added  $P_D$  due to short circuit test; e.g.,  $I_{OS}$ .

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## 2. APPLICABLE DOCUMENTS

2.1 Government specification, standard, and bulletin. Unless otherwise specified, the following specification, standard, and bulletin of the issue listed in that issue of the Department of Defense Index of Specifications and Standards specified in the solicitation, form a part of this drawing to the extent specified herein.

### SPECIFICATION

#### MILITARY

MIL-M-38510 - Microcircuits, General Specification for.

### STANDARD

#### MILITARY

MIL-STD-883 - Test Methods and Procedures for Microelectronics.

### BULLETIN

#### MILITARY

MIL-BUL-103 - List of Standardized Military Drawings (SMD's).

(Copies of the specification, standard, and bulletin required by manufacturers in connection with specific acquisition functions should be obtained from the contracting activity or as directed by the contracting activity.)

2.2 Order of precedence. In the event of a conflict between the text of this drawing and the references cited herein, the text of this drawing shall take precedence.

## 3. REQUIREMENTS

3.1 Item requirements. The individual item requirements shall be in accordance with 1.2.1 of MIL-STD-883, "Provisions for the use of MIL-STD-883 in conjunction with compliant non-JAN devices" and as specified herein.

3.2 Design, construction, and physical dimensions. The design, construction, and physical dimensions shall be as specified in MIL-M-38510 and herein.

3.2.1 Terminal connections. The terminal connections shall be as specified on figure 1.

3.2.2 Truth table. The truth table shall be as specified on figure 2.

3.2.3 Logic diagram. The logic diagram shall be as specified on figure 3.

3.2.4 Case outlines. The case outlines shall be in accordance with 1.2.2 herein.

3.3 Electrical performance characteristics. Unless otherwise specified herein, the electrical performance characteristics are as specified in table I and apply over the full case operating temperature range.

3.4 Electrical test requirements. The electrical test requirements shall be the subgroups specified in table II. The electrical tests for each subgroup are described in table I.

3.5 Marking. Marking shall be in accordance with MIL-STD-883 (see 3.1 herein). The part shall be marked with the part number listed in 1.2 herein. In addition, the manufacturer's part number may also be marked as listed in MIL-BUL-103 (see 6.6 herein).

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TABLE 1. Electrical performance characteristics.

Test	Symbol	Conditions -55°C < T <sub>C</sub> < +125°C V <sub>CC</sub> = 5.0 V dc ±10% unless otherwise specified	Device type	Group A subgroups	Limits		Unit
					Min	Max	
High level output voltage	V <sub>OH</sub>	V <sub>CC</sub> = 4.5 V, V <sub>IL</sub> = 0.8 V, V <sub>IH</sub> = 2.0 V	I <sub>OH</sub> = -300 μA	A11	1, 2, 3	4.3	V
			I <sub>OH</sub> = -12 mA	A11	1, 2, 3	2.4	
Low level output voltage	V <sub>OL</sub>	V <sub>CC</sub> = 4.5 V, V <sub>IL</sub> = 0.8 V, V <sub>IH</sub> = 2.0 V	I <sub>OL</sub> = 300 μA	A11	1, 2, 3		V
			I <sub>OL</sub> = 48 mA	A11	1, 2, 3	0.55	
Input clamp voltage	V <sub>IK</sub>	V <sub>CC</sub> = 4.5 V, I <sub>IN</sub> = -18 mA	A11	1, 2, 3		-1.2	V
High level input current	I <sub>IH</sub>	V <sub>CC</sub> = 5.5 V, V <sub>IN</sub> = 5.5 V	A11	1, 2, 3		5.0	μA
Low level input current	I <sub>IL</sub>	V <sub>CC</sub> = 5.5 V, V <sub>IN</sub> = GND	A11	1, 2, 3		-5.0	μA
High impedance output current	I <sub>OZH</sub>	V <sub>CC</sub> = 5.5 V, V <sub>IN</sub> = 5.5 V	A11	1, 2, 3		10	μA
	I <sub>OZL</sub>	V <sub>CC</sub> = 5.5 V, V <sub>IN</sub> = GND	A11	1, 2, 3		-10	μA
Short circuit output current	I <sub>OS</sub>	V <sub>CC</sub> = 5.5 V, <u>1</u> / V <sub>O</sub> = GND	A11	1, 2, 3		-60	mA
Quiescent power supply current (CMOS inputs)	I <sub>CCQ</sub>	V <sub>IN</sub> < 0.2 V or V <sub>IN</sub> > 5.3 V, V <sub>CC</sub> = 5.5 V, f <sub>I</sub> = 0 MHz	A11	1, 2, 3		1.5	mA
Quiescent power supply current (TTL inputs)	ΔI <sub>CC</sub>	V <sub>CC</sub> = 5.5 V, V <sub>IN</sub> = 3.4 V <u>2</u> /	A11	1, 2, 3		2.0	mA
Dynamic power supply current	I <sub>CCD</sub>	V <sub>CC</sub> = 5.5 V, <u>0</u> En = GND, one bit toggling, 50% duty cycle, V <sub>IN</sub> > 5.3 V or V <sub>IN</sub> < 0.2 V, outputs open	A11	<u>3</u> /		0.4	mA/ MHz

See footnotes at end of table.

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TABLE I. Electrical performance characteristics - Continued.

Test	Symbol	Conditions -55°C < T <sub>C</sub> < +125°C V <sub>CC</sub> = 5.0 V dc ±10% unless otherwise specified	Device type	Group A subgroups	Limits		Unit	
					Min	Max		
Total power supply current	I <sub>CC</sub>	V <sub>CC</sub> = 5.5 V, outputs open, f <sub>i</sub> = 10 MHz, 50% duty cycle, one bit toggling, OEn = GND 4/	V <sub>IN</sub> ≥ 5.3 V or V <sub>IN</sub> ≤ 0.2 V	A11	1, 2, 3		5.5	mA
			V <sub>IN</sub> = 3.4 V or V <sub>IN</sub> = GND	A11	1, 2, 3		6.0	mA
Input capacitance	C <sub>IN</sub>	See 4.3.1c	A11	4		10	pF	
Output capacitance	C <sub>OUT</sub>	See 4.3.1c	A11	4		12	pF	
Functional tests		See 4.3.1d	A11	7, 8				
Propagation delay time, Dn to On	t <sub>PLH</sub> , t <sub>PHL</sub>	C <sub>L</sub> = 50 pF, R <sub>L</sub> = 500Ω, see figure 4 5/	01	9, 10, 11	2.0	9.0	ns	
			02		2.0	5.1		
Output enable time	t <sub>pZH</sub> , t <sub>pZL</sub>		01	9, 10, 11	2.0	12.5	ns	
			02		2.0	6.5		
Output disable time	t <sub>pHZ</sub> , t <sub>pLZ</sub>		01	9, 10, 11	2.0	12.5	ns	
			02		2.0	5.9		

1/ Not more than one output should be shorted at one time, and the duration of the short circuit condition should not exceed 1 second.

2/ TTL driven input (V<sub>IN</sub> = 3.4 V); all other inputs at V<sub>CC</sub> or GND.

3/ This parameter is not directly testable, but is derived for use in total power supply calculations.

4/ I<sub>CC</sub> = I<sub>CCQ</sub> + (ΔI<sub>CC</sub> × D<sub>H</sub> × N<sub>T</sub>) + (I<sub>CCD</sub> × f<sub>I</sub> × N<sub>I</sub>) where:

D<sub>H</sub> = Duty cycle for TTL inputs high.

N<sub>T</sub> = Number of TTL inputs at D<sub>H</sub>.

f<sub>I</sub> = Input frequency in MHz.

N<sub>I</sub> = Number of inputs at f<sub>I</sub>.

5/ The minimum limits are guaranteed, if not tested, to the limits specified in table I.

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Device types	01 and 02
Case outlines	R, S, and 2
Terminal number	Terminal symbol
1	0EA
2	D0
3	D1
4	D2
5	D3
6	D4
7	D5
8	D6
9	D7
10	GND
11	07
12	06
13	05
14	04
15	03
16	02
17	01
18	00
19	0EB
20	VCC

FIGURE 1. Terminal connections.

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Device types 01 and 02		
Inputs		Outputs
$\overline{OE}A, \overline{OE}B$	Dn	On
L	L	L
L	H	H
H	X	Z

H = High voltage level  
L = Low voltage level  
X = Irrelevant  
Z = High impedance

FIGURE 2. Truth table.

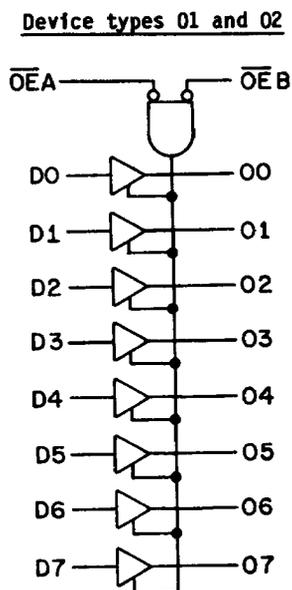


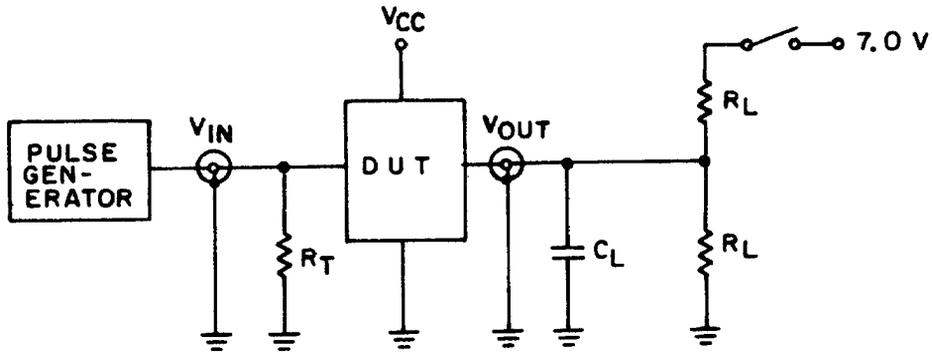
FIGURE 3. Logic diagram.

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Device types 01 and 02



Switch position

Test	Switch
$t_{PLZ}$	Closed
$t_{PZL}$	Closed
All other	Open

Definitions:

- $R_L$  = Load capacitor. See ac characteristics for value.
- $C_L$  = Load capacitance, including jig and probe capacitance. See ac characteristics for value.
- $R_T$  = Termination resistance should be equal to  $Z_{OUT}$  of pulse generator.

FIGURE 4. Test circuit and switching waveforms.

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Device types 01 and 02

PROPAGATION DELAY

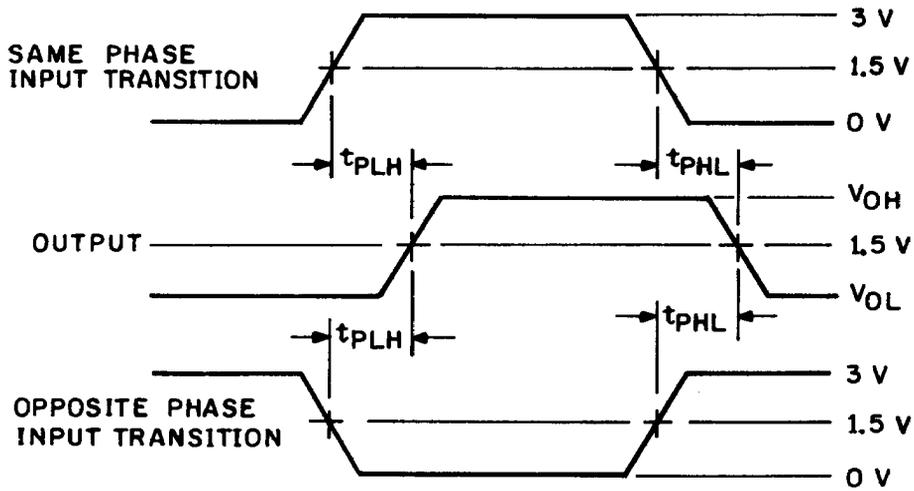


FIGURE 4. Test circuit and switching waveforms - Continued.

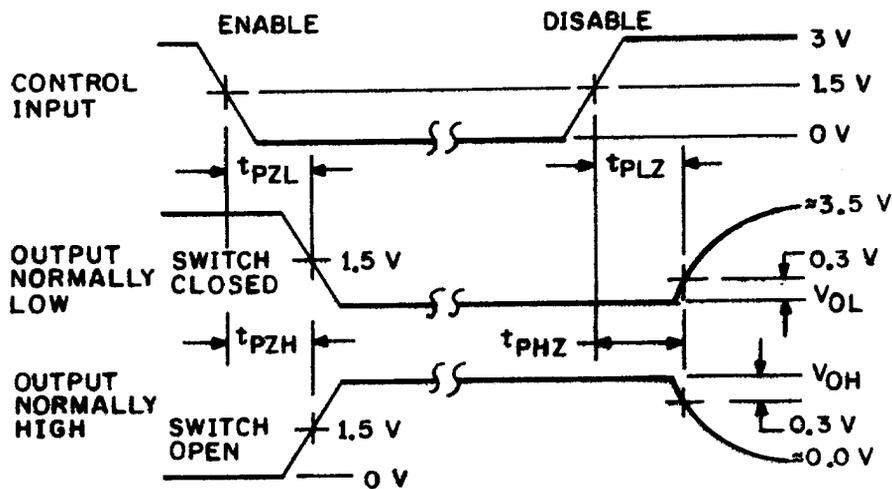
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Device types 01 and 02

ENABLE AND DISABLE TIMES



NOTES:

1. Diagram shown for input control enable (low) and input control disable (high).
2. Pulse generator for all pulses:  $t_f \leq 2.5$  ns;  $t_r \leq 2.5$  ns.

FIGURE 4. Test circuit and switching waveforms - Continued.

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3.6 Certificate of compliance. A certificate of compliance shall be required from a manufacturer in order to be listed as an approved source of supply in MIL-BUL-103 (see 6.6 herein). The certificate of compliance submitted to DESC-ECS prior to listing as an approved source of supply shall affirm that the manufacturer's product meets the requirements of MIL-STD-883 (see 3.1 herein) and the requirements herein.

3.7 Certificate of conformance. A certificate of conformance as required in MIL-STD-883 (see 3.1 herein) shall be provided with each lot of microcircuits delivered to this drawing.

3.8 Notification of change. Notification of change to DESC-ECS shall be required in accordance with MIL-STD-883 (see 3.1 herein).

3.9 Verification and review. DESC, DESC's agent, and the acquiring activity retain the option to review the manufacturer's facility and applicable required documentation. Offshore documentation shall be made available onshore at the option of the reviewer.

4. QUALITY ASSURANCE PROVISIONS

4.1 Sampling and inspection. Sampling and inspection procedures shall be in accordance with section 4 of MIL-M-38510 to the extent specified in MIL-STD-883 (see 3.1 herein).

4.2 Screening. Screening shall be in accordance with method 5004 of MIL-STD-883, and shall be conducted on all devices prior to quality conformance inspection. The following additional criteria shall apply:

- a. Burn-in test, method 1015 of MIL-STD-883.
  - (1) Test condition A, B, C, or D using the circuit submitted with the certificate of compliance (see 3.6 herein).
  - (2)  $T_A = +125^{\circ}\text{C}$ , minimum.
- b. Interim and final electrical test parameters shall be as specified in table II herein, except interim electrical parameter tests prior to burn-in are optional at the discretion of the manufacturer.

4.3 Quality conformance inspection. Quality conformance inspection shall be in accordance with method 5005 of MIL-STD-883 including groups A, B, C, and D inspections. The following additional criteria shall apply.

4.3.1 Group A inspection.

- a. Tests shall be as specified in table II herein.
- b. Subgroups 5 and 6 in table I, method 5005 of MIL-STD-883 shall be omitted.
- c. Subgroup 4 ( $C_{IN}$  and  $C_{OUT}$  measurements) shall be measured only initially and after process or design changes which may affect capacitance. Test all applicable pins on five devices with zero failures.
- d. Subgroups 7 and 8 shall verify the truth table as specified on figure 2.

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4.3.2 Groups C and D inspections.

- a. End-point electrical parameters shall be as specified in table II herein.
- b. Steady-state life test conditions, method 1005 of MIL-STD-883.
  - (1) Test condition A, B, C, or D using the circuit submitted with the certificate of compliance (see 3.6 herein).
  - (2)  $T_A = +125^{\circ}\text{C}$ , minimum.
  - (3) Test duration: 1,000 hours, except as permitted by method 1005 of MIL-STD-883.

TABLE II. Electrical test requirements.

MIL-STD-883 test requirements	Subgroups (per method 5005, table I)
Interim electrical parameters (method 5004)	---
Final electrical test parameters (method 5004)	1*, 2, 3, 7, 8, 9, 10, 11
Group A test requirements (method 5005)	1, 2, 3, 4, 7, 8, 9, 10, 11
Groups C and D end-point electrical parameters (method 5005)	1, 2, 3

\* PDA applies to subgroup 1.

5. PACKAGING

5.1 Packaging requirements. The requirements for packaging shall be in accordance with MIL-M-38510.

6. NOTES

6.1 Intended use. Microcircuits conforming to this drawing are intended for use when military specifications do not exist and qualified military devices that will perform the required function are not available for OEM application. When a military specification exists and the product covered by this drawing has been qualified for listing on QPL-38510, the device specified herein will be inactivated and will not be used for new design. The QPL-38510 product shall be the preferred item for all applications.

6.2 Replaceability. Microcircuits covered by this drawing will replace the same generic device covered by a contractor-prepared specification or drawing.

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6.3 Configuration control of SMD's. All proposed changes to existing SMD's will be coordinated with the users of record for the individual documents. This coordination will be accomplished in accordance with MIL-STD-481 using DD Form 1693, Engineering Change Proposal (Short Form).

6.4 Record of users. Military and industry users shall inform Defense Electronics Supply Center when a system application requires configuration control and the applicable SMD. DESC will maintain a record of users and this list will be used for coordination and distribution of changes to the drawings. Users of the drawing covering microelectronics devices (FSC 5962) should contact DESC-ECS, telephone (513) 296-6022.

6.5 Comments. Comments on this drawing should be directed to DESC-ECS, Dayton, Ohio 45444, or telephone (513) 296-5375.

6.6 Approved sources of supply. Approved sources of supply are listed in MIL-BUL-103. Additional sources will be added to MIL-BUL-103 as they become available. The vendors listed in MIL-BUL-103 have agreed to this drawing and a certificate of compliance (see 3.6 herein) has been submitted to and accepted by DESC-ECS. The approved sources of supply listed below are for information purposes only and are current only to the date of the last action of this document.

Military drawing part number	Vendor CAGE number	Vendor similar part number <u>1/</u>
5962-8976601RX	61772 27014	IDT54FCT541DB 54FCT541DMQB
5962-8976601SX	61772 27014	IDT54FCT541EB 54FCT541FMQB
5962-89766012X	61772 27014	IDT54FCT541LB 54FCT541LMQB
5962-8976602RX	61772	IDT54FCT541ADB
5962-8976602SX	61772	IDT54FCT541AEB
5962-89766022X	61772	IDT54FCT541ALB

1/ Caution. Do not use this number for item acquisition. Items acquired to this number may not satisfy the performance requirements of this drawing.

Vendor CAGE number

Vendor name and address

27014

National Semiconductor  
333 Western Avenue  
South Portland, ME 04106

61772

Integrated Device Technology  
3236 Scott Boulevard  
Santa Clara, CA 95054

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